

## PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hua Ji</td><td>06/02/2008</td></tr><tr><td>Min-Hwa Chi</td><td>05/29/2008</td></tr><tr><td>Fumitake Mieno</td><td>06/02/2008</td></tr></tbody></table>		Name	Execution Date	Hua Ji	06/02/2008	Min-Hwa Chi	05/29/2008	Fumitake Mieno	06/02/2008
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Hua Ji	06/02/2008								
Min-Hwa Chi	05/29/2008								
Fumitake Mieno	06/02/2008								
RECEIVING PARTY DATA									
Name:	Semiconductor Manufacturing International (Shanghai) Corporation								
Street Address:	18 Zhang Jiang Road, Pudong New Area								
City:	Shanghai								
State/Country:	CHINA								
Postal Code:	201210								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12132459</td></tr></tbody></table>		Property Type	Number	Application Number:	12132459				
Property Type	Number								
Application Number:	12132459								
CORRESPONDENCE DATA									
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Total Attachments: 2 source=88644.43assign#page1.tif source=88644.43assign#page2.tif									

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PATENT  
REEL: 021044 FRAME: 0991

# ASSIGNMENT

Insert Name(s) of Inventor(s)

(1) Hua JI

(2) Min-Hwa CHI

(3) Fumitake MIENO

For good and valuable consideration, receipt of which is hereby acknowledged, the undersigned agrees to assign, hereby does assign, transfer and set over to:

(5) Insert Name of Assignee (5) **Semiconductor Manufacturing International (Shanghai) Corporation**

(6) Insert Address of Assignee (6) **of: 18 Zhang Jiang Road, Pudong New Area, Shanghai, 201210 P.R. China** (hereinafter designated as the Assignee) the entire worldwide right, title, interest, and patent applications an patents for every country, including divisions, reissues, continuations and all other extensions, rights and priorities in the invention known as and related to

(7) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number (7) Title: Atomic Layer deposition Method and Semiconductor Device Formed by The Same

Attorney Docket No. 88644.43 Serial No.: 12/132,459 for which the undersigned has executed an application for patent in the United States of America

(8) Insert Date of Signing of Application (8) on (1) 6/2/08 (2) 5/29/08 (3) 6/2/08

- 1) The undersigned agrees to execute all papers necessary in connection with the application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.
- 2) The undersigned agrees to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.
- 3) The undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

- 4) The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.
- 5) The undersigned hereby authorizes and requests the Commissioner of Patents and the duly constituted authorities of foreign countries to issue any and all Letters Patents resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, its successors and assigns, as Assignee of the entire right, title and interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has not executed and will not execute any agreement in conflict herewith.
- 6) *The undersigned hereby grant(s)*

Song Zhu, Reg. No. 44,420

Cameron K. Kerrigan, Reg. No. 44,826; Mark Lupkowski, Reg. No. 49,010; Zhaoyang Li, Reg. No. 46,872; Bernard F. Rose, Reg. No. 42,112; Angie Augustus, Reg. No. 51,421; Jeff Talkington, Reg. No. 58,381; Ram Sabnis, Reg. No. 58,868.

*the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.*

Date Jun. 2, 2008

Signature of Inventor: Ji Hua  
Hua Ji

Date May 29, 2008

Signature of Inventor: Min-Hwa Chi  
Min-Hwa CHI

Date June 2, 2008

Signature of Inventor: F. Miemo  
Fumitake MIENO